

REMARKS

Applicants appreciate the detailed examination of the present application evidenced by the final Office Action mailed August 25, 2006 ("Final Action") and the Advisory Action mailed November 2, 2006 ("Advisory Action"). Applicants do not acquiesce in the assertions of the Final Action and the Advisory Action and, in the interest of brevity, reiterate the arguments presented in Applicants' Amendment filed October 24, 2006 by incorporating those remarks by reference herein. In order to further clarify the nature of the claimed subject matter, however, Applicants have amended independent Claims 1, 12, 23 and 27 as set forth above. Applicants respectfully submit that the claims, as amended, are patentable over the cited references for at least the additional reasons discussed below.

The Final Action rejects independent Claims 1, 12, 23 and 27 as allegedly anticipated by U.S. Patent No. Re 36,469 to Wood et al. ("Wood"). Final Action, p. 2. The Advisory Action appears to maintain these rejections, but confusingly states "the claimed structure is held prima facie obvious over Wood and Saia references for the reasons stated in the last Office Action mailed 8/25/06." Advisory Action, Continuation Sheet. Should this be intended as a new basis for the rejections of independent Claims 1, 12, 23, and 27, Applicants request clarification as such in the response to this paper. The remarks herein assume that the bases for the rejections of Claims 1, 12, 23 and 27 are as set forth in the Final Action.

Claim 1 has been amended to recite:

An electronic module, comprising:

a monolithic microelectronic substrate including a plurality of integrated circuit dice and a redistribution structure across the dice thereon providing an edge connector contact coupled to at least one of the plurality of integrated circuit dice, the edge connector contact configured for mating with a contact of an edge connector that is configured to engage an edge of the substrate, *wherein the plurality of dice are connected to one another via the redistribution structure.*

Independent Claims 12, 23 and 27 have been similarly amended. Applicants submit that Wood does not disclose or suggest such recitations.

In particular, the Final Action cites FIGs. 3, 5, 8 and 12 of Wood as teaching the recitations of Claim 1. *See* Final Action, p. 2. As Applicants have previously noted, the embodiments in FIGs. 3, 5 and 12 are not "monolithic microelectronic substrates" as recited in Claim 1. Rather, FIGs. 3, 5 and 12 show multi-component structures in which a flex circuit 12 is attached to the underlying die 10 by solder bumps. *See, e.g.,* Wood, column 8,

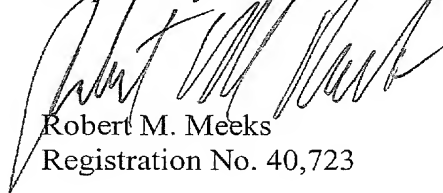
lines 16-20. For at least these reasons, the structures shown in FIGs. 3, 5 and 12 and the textual description thereof do not disclose or suggest the recitations of amended Claim 1.

FIG. 8 shows a monolithic substrate including a single die 10 with layers 16, including conductive and insulative layers, added thereto. There is no disclosure or suggestion in Wood that the conductive layers provide interconnection among a plurality of dice. Accordingly, FIG. 8 of Wood and the description thereof does not disclose or suggest the recitations of amended independent Claim 1.

For at least the foregoing additional reasons, Applicants submit that amended independent Claim 1 is patentable. At least similar additional reasons support the patentability of amended independent Claims 12, 23 and 27. Applicants further submit that dependent Claims 3-11, 13-22, 24-26, and 28-39 are patentable at least by virtue of the patentability of the respective ones of independent Claims 1, 12, 23 and 27 from which they depend, and that several of the dependent claims are separately patentable for at least the reasons discussed in Applicants' Amendment filed October 24, 2006.

As all of the claims are now in condition for allowance, Applicants respectfully request allowance of the claims and passing of the application to issue in due course. Applicants urge the Examiner to contact Applicants' undersigned representative at (919) 854-1400 to resolve any remaining formal issues.

Respectfully submitted,



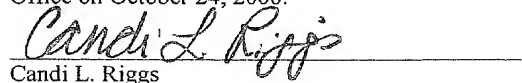
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I hereby certify that this correspondence is being transmitted electronically to the U.S. Patent and Trademark Office on October 24, 2006.



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